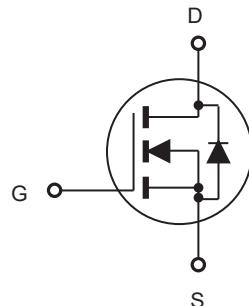
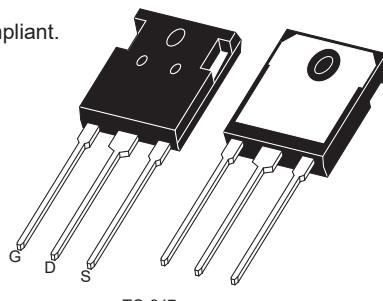


N-Channel Enhancement Mode Field Effect Transistor

FEATURES

Type	$V_{DSS}@T_J \text{ max}$	$R_{DS(\text{ON})}$	I_D	@ V_{GS}
CEW33N60S	650V	115mΩ	33A	10V

- Super high dense cell design for extremely low $R_{DS(\text{ON})}$.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- TO-247 package.

ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current-Continuous @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	I_D	33 21	A
Drain Current-Pulsed ^a	I_{DM}	132	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	312 2.5	W W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy ^d	E_{AS}	375	mJ
Single Pulsed Avalanche Current ^d	I_{AS}	5	A
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.4	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$



CEW33N60S

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units	
Off Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	600			V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA	
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA	
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA	
On Characteristics^b							
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V	
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 14.5\text{A}$		104	115	$\text{m}\Omega$	
Gate Input Resistance	R_g	f=1MHz,open Drain		2.7		Ω	
Dynamic Characteristics^c							
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2900		pF	
Output Capacitance	C_{oss}			1795		pF	
Reverse Transfer Capacitance	C_{rss}			100		pF	
Switching Characteristics^c							
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$		57		ns	
Turn-On Rise Time	t_r			84		ns	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			269		ns	
Turn-Off Fall Time	t_f			74		ns	
Total Gate Charge	Q_g	$V_{\text{DS}} = 480\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		78		nC	
Gate-Source Charge	Q_{gs}			13		nC	
Gate-Drain Charge	Q_{gd}			36		nC	
Drain-Source Diode Characteristics and Maximum Ratings							
Drain-Source Diode Forward Current	I_S				33	A	
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 33\text{A}$			1.4	V	
Reverse Recovery Time	T_{rr}	$I_F = 33\text{A}, \text{di}/dt = 100\text{A/us}$		595		ns	
Reverse Recovery Charge	Q_{rr}			9		uC	
Peak Reverse Recovery Current	I_{rr}			35		A	
Notes :							
a.Repetitive Rating : Pulse width limited by maximum junction temperature.							
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.							
c.Guaranteed by design, not subject to production testing.							
d.L = 30mH, $I_{AS} = 5\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.							

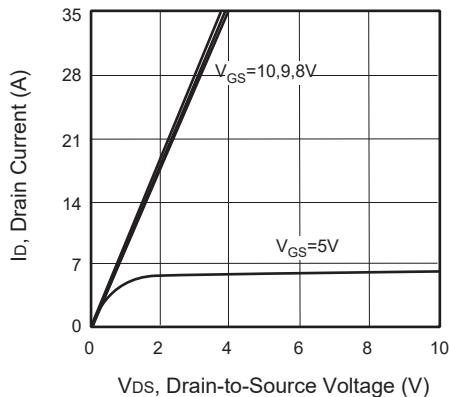


Figure 1. Output Characteristics

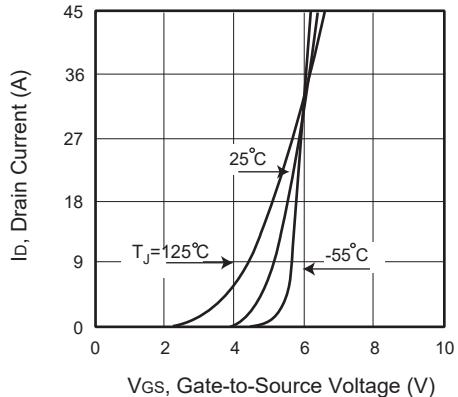


Figure 2. Transfer Characteristics

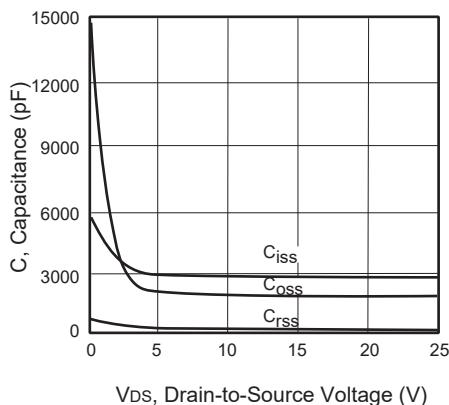


Figure 3. Capacitance

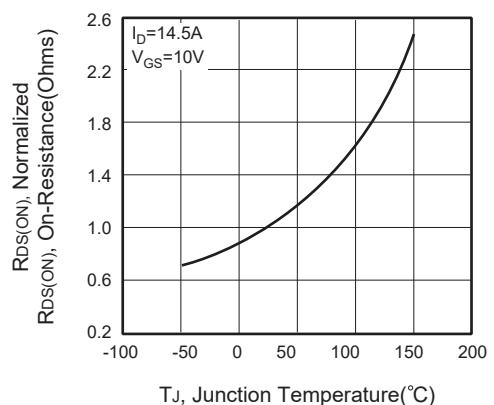


Figure 4. On-Resistance Variation with Temperature

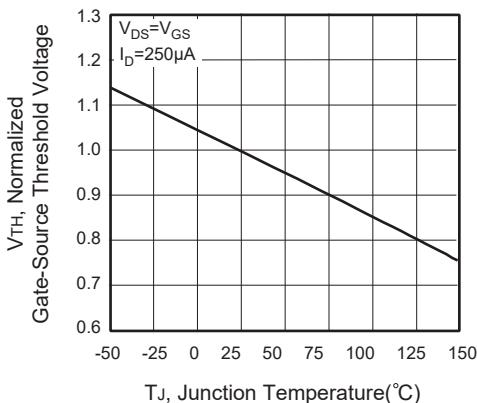


Figure 5. Gate Threshold Variation with Temperature

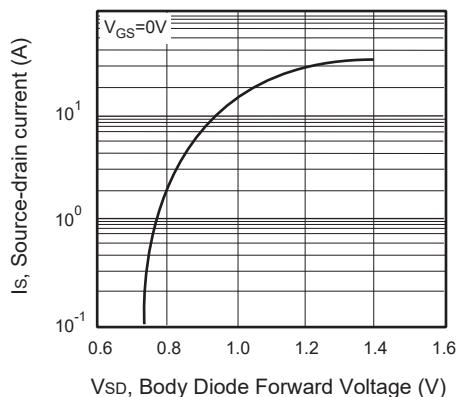


Figure 6. Body Diode Forward Voltage Variation with Source Current

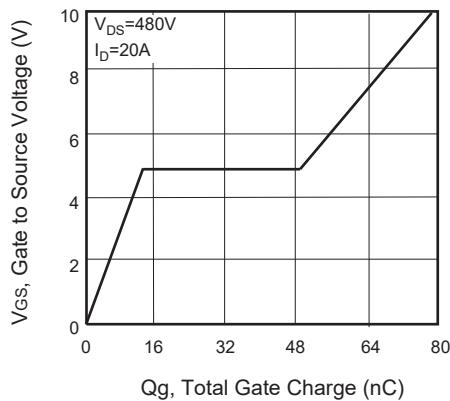


Figure 7. Gate Charge

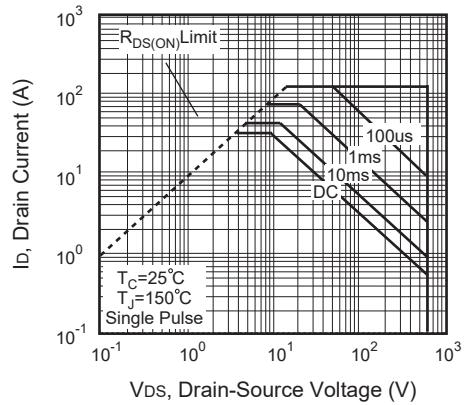


Figure 8. Maximum Safe Operating Area

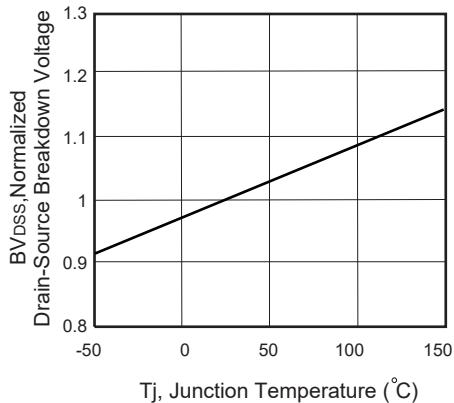


Figure 9. Breakdown Voltage Variation VS Temperature

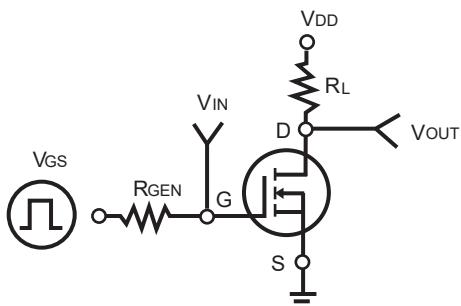


Figure 10. Switching Test Circuit

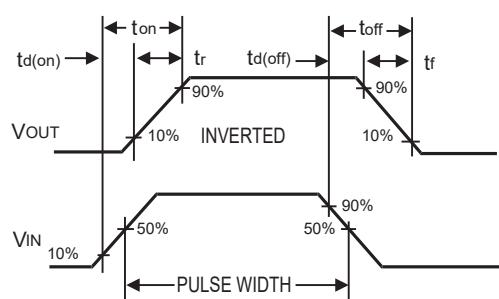


Figure 11. Switching Waveforms

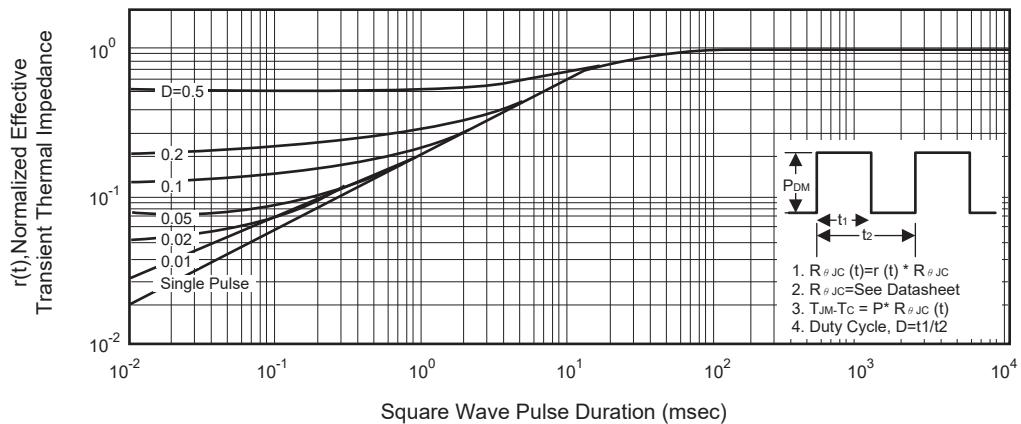
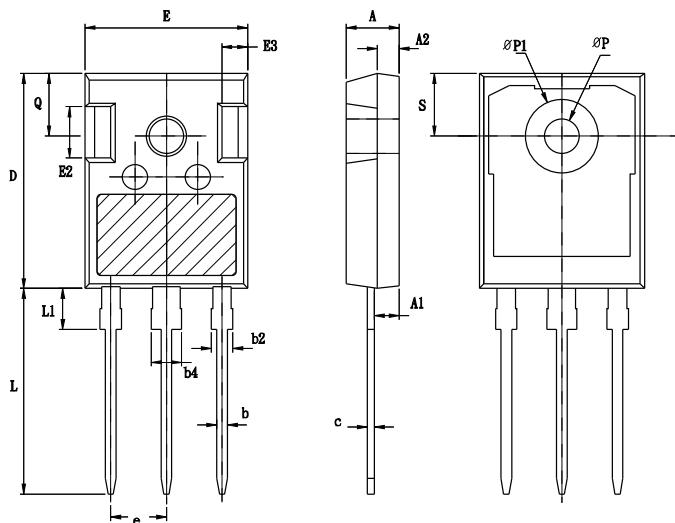


Figure 12. Normalized Thermal Transient Impedance Curve

TO-247 產品外觀尺寸圖 (Product Outline Dimension)



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.830	5.210	0.190	0.205
A1	2.310	2.510	0.091	0.099
A2	1.900	2.160	0.075	0.085
b	1.140	1.400	0.045	0.055
b2	1.910	2.200	0.075	0.087
b4	2.960	3.160	0.117	0.124
C	0.550	0.750	0.022	0.030
D	20.800	21.340	0.819	0.840
e	5.45BSC		0.215BSC	
E	15.700	16.130	0.618	0.635
E2	4.320	5.100	0.170	0.201
E3	1.58	2.60	0.062	0.102
L	19.80	20.57	0.780	0.810
L1	3.81	4.32	0.150	0.170
ΦP	3.5	3.7	0.138	0.146
ΦP1	~	7.3	~	0.287
S	6.15BSC		0.242BSC	
Q	5.59	6.2	0.220	0.244